IEEE MTT-S Latin America Microwave Conference

Buenos Aires, Argentina
December 9-11, 2026

LAMC 2026 Buenos Aires

LAMC — IEEE MTT-S LATIN AMERICA MICROWAVE CONFERENCE

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The sixth edition of LAMC will take place in Buenos Aires, Argentina, on December 9-11, 2026. After five successful editions in Puerto Vallarta, Mexico (2016), Arequipa, Peru (2018), Cali, Colombia (2021, virtual), San José, Costa Rica (2023), and San Juan, Puerto Rico (2025), LAMC goes to Buenos Aires as a high-quality technical forum for the Latin America region and all the MTT-S community. Buenos Aires is the vibrant capital of Argentina, known for its rich cultural heritage, European-style architecture, and lively atmosphere. The city offers a unique blend of history, art, tango music, world-class cuisine, nightlife, and charming neighborhoods.

We encourage the submission of original, unpublished research focused on (but not limited to) the following topics of interest:

1. **Passive components, circuits, and devices** (planar and nonplanar components and circuits, filters and multiplexers, tunable devices, and metamaterials).

2. **Active devices, circuits, and measurement systems** (RFICs & MMIC design, power amplifiers, linearization techniques, low-noise circuits, signal generation, conversion & control modules, linear and non-linear modeling, and measurement techniques.

3. **RF systems and applications** (microwave systems, front-ends, industrial, scientific and medical applications, navigation systems, intelligent transportation systems, imaging, sensors, and wireless power transmission).

4. **Communication systems** (terrestrial, vehicular, satellite, and indoor applications, and wireless and cellular communication systems).

5. **Active and passive antennas** (phased arrays, integrated antennas, smart antennas, digital beamforming, and MIMO).

6. **Signal-power integrity and high-speed digital techniques** (EM interference and compatibility, high-speed interconnects, post-silicon validation techniques, power delivery networks, computer simulations, and measurements).

7. **CAD techniques for RF and microwave engineering** (surrogate-based modeling and optimization, space mapping-based methods, model order reduction, machine learning approaches, statistical analysis and design, EM-based and multi-physics design optimization, EM field theory, and time- and frequency-domain numerical techniques).

Papers submitted to LAMC 2026 will be peer reviewed and evaluated based on originality, quantitative content, clarity, and interest to the audience. The review process will be single-blind. LAMC will use EDAS as the electronic paper management system. All accepted and presented papers will be published in the LAMC Conference Proceedings and submitted for inclusion in the *IEEE Xplore Digital Library*.

English will be the official language of the conference. Prospective authors are cordially invited to submit a three-page two-column manuscript, following the instructions available at the conference website (https://lamc-ieee.org).

Important Dates

Proposals for special sessions and tutorials:	July 20, 2026
Submission regular papers:	August 3, 2026
Notification of acceptance:	September 11, 2026
Camera-ready submission:	October 9, 2026
Author registration deadline:	October 19, 2026

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